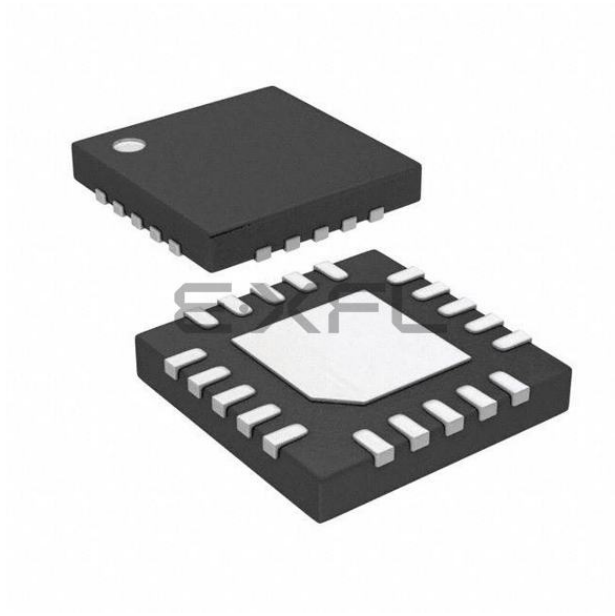

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

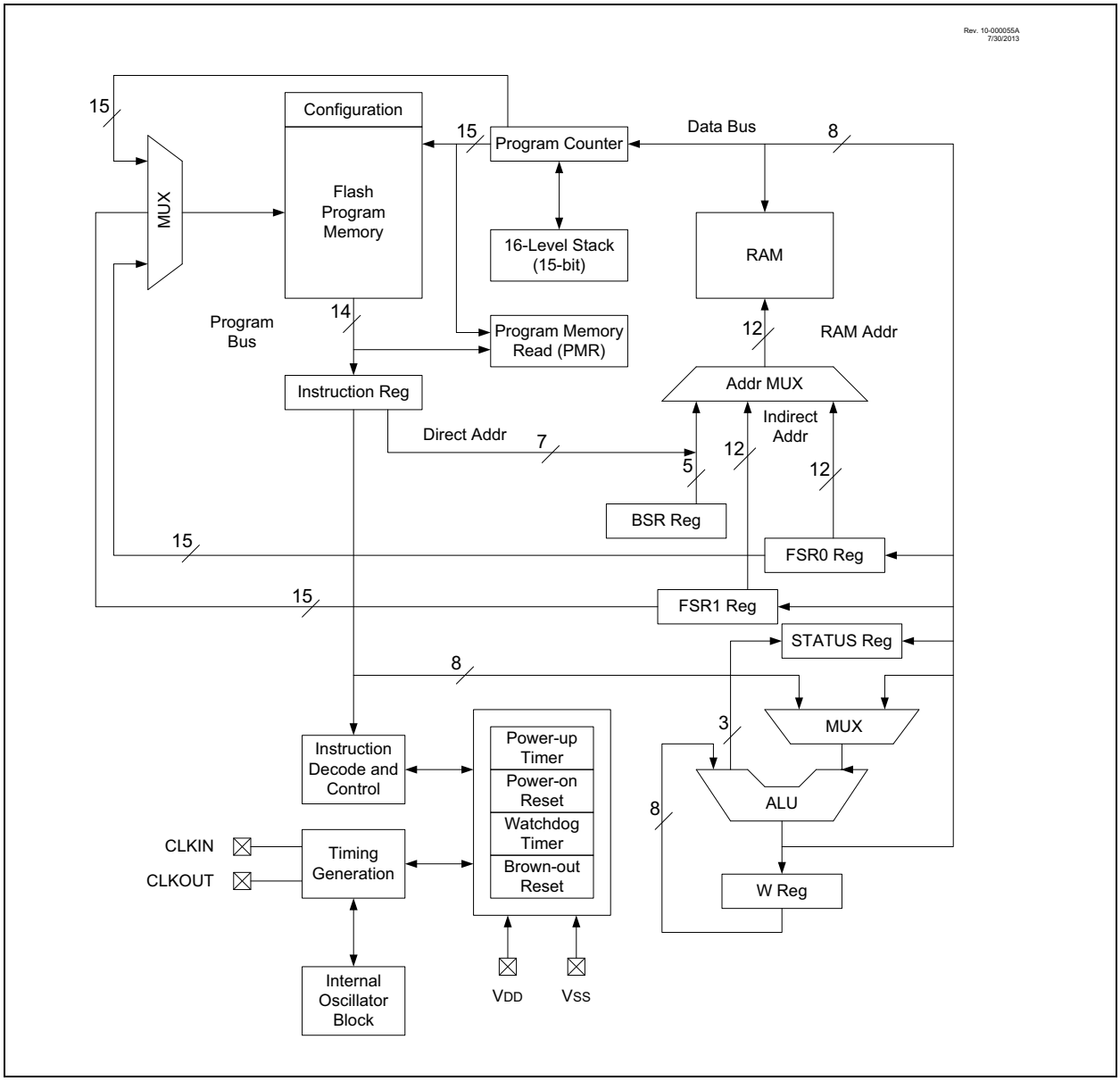
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	LINbus, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	18
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-UFQFN Exposed Pad
Supplier Device Package	20-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1579-i-gz

2.0 ENHANCED MID-RANGE CPU

This family of devices contain an enhanced mid-range 8-bit CPU core. The CPU has 49 instructions. Interrupt capability includes automatic context saving. The hardware stack is 16 levels deep and has Overflow and Underflow Reset capability. Direct, Indirect, and Relative addressing modes are available. Two File Select Registers (FSRs) provide the ability to read program and data memory.

- Automatic Interrupt Context Saving
- 16-level Stack with Overflow and Underflow
- File Select Registers
- Instruction Set

FIGURE 2-1: CORE BLOCK DIAGRAM



4.7 Register Definitions: Device ID

REGISTER 4-3: DEVICEID: DEVICE ID REGISTER(1)

R	R	R	R	R	R
DEV<13:8>					
bit 13					bit 8

R	R	R	R	R	R	R	R
DEV<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit		
'0' = Bit is cleared	'1' = Bit is set	x = Bit is unknown

bit 13-0 **DEV<13:0>:** Device ID bits
Refer to Table 4-1 to determine what these bits will read on which device. A value of 3FFFh is invalid.

Note 1: This location cannot be written.

REGISTER 4-4: REVISIONID: REVISION ID REGISTER(1)

R	R	R	R	R	R
REV<13:8>					
bit 13					bit 8

R	R	R	R	R	R	R	R
REV<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit		
'0' = Bit is cleared	'1' = Bit is set	x = Bit is unknown

bit 13-0 **REV<13:0>:** Revision ID bits
These bits are used to identify the device revision.

Note 1: This location cannot be written.

TABLE 4-1: DEVICE ID VALUES

DEVICE	Device ID	Revision ID
PIC16F1574	3000h	2xxxh
PIC16F1575	3001h	2xxxh
PIC16F1578	3002h	2xxxh
PIC16F1579	3003h	2xxxh
PIC16LF1574	3004h	2xxxh
PIC16LF1575	3005h	2xxxh
PIC16LF1578	3006h	2xxxh
PIC16LF1579	3007h	2xxxh

TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH CLOCK SOURCES

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
OSCCON	SPLLEN	IRCF<3:0>				—	SCS<1:0>		69
OSCSTAT	—	PLLR	OSTS	HFIOFR	HFIOFL	MFIOFR	LFIOFR	HFIOFS	70
OSCTUNE	—	—	TUN<5:0>						71

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by clock sources.

TABLE 5-3: SUMMARY OF CONFIGURATION WORD WITH CLOCK SOURCES

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	—	—	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		—	56
	7:0	$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		—	FOSC<1:0>		

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by clock sources.

7.1 Operation

Interrupts are disabled upon any device Reset. They are enabled by setting the following bits:

- GIE bit of the INTCON register
- Interrupt Enable bit(s) for the specific interrupt event(s)
- PEIE bit of the INTCON register (if the Interrupt Enable bit of the interrupt event is contained in the PIE1, PIE2 and PIE3 registers)

The INTCON, PIR1, PIR2 and PIR3 registers record individual interrupts via interrupt flag bits. Interrupt flag bits will be set, regardless of the status of the GIE, PEIE and individual interrupt enable bits.

The following events happen when an interrupt event occurs while the GIE bit is set:

- Current prefetched instruction is flushed
- GIE bit is cleared
- Current Program Counter (PC) is pushed onto the stack
- Critical registers are automatically saved to the shadow registers (See **"Section 7.5 "Automatic Context Saving"."**)
- PC is loaded with the interrupt vector 0004h

The firmware within the Interrupt Service Routine (ISR) should determine the source of the interrupt by polling the interrupt flag bits. The interrupt flag bits must be cleared before exiting the ISR to avoid repeated interrupts. Because the GIE bit is cleared, any interrupt that occurs while executing the ISR will be recorded through its interrupt flag, but will not cause the processor to redirect to the interrupt vector.

The `RETFIE` instruction exits the ISR by popping the previous address from the stack, restoring the saved context from the shadow registers and setting the GIE bit.

For additional information on a specific interrupt's operation, refer to its peripheral chapter.

Note 1:	Individual interrupt flag bits are set, regardless of the state of any other enable bits.
2:	All interrupts will be ignored while the GIE bit is cleared. Any interrupt occurring while the GIE bit is clear will be serviced when the GIE bit is set again.

7.2 Interrupt Latency

Interrupt latency is defined as the time from when the interrupt event occurs to the time code execution at the interrupt vector begins. The latency for synchronous interrupts is three or four instruction cycles. For asynchronous interrupts, the latency is three to five instruction cycles, depending on when the interrupt occurs. See Figure 7-2 and Figure 7-3 for more details.

10.2.3 ERASING FLASH PROGRAM MEMORY

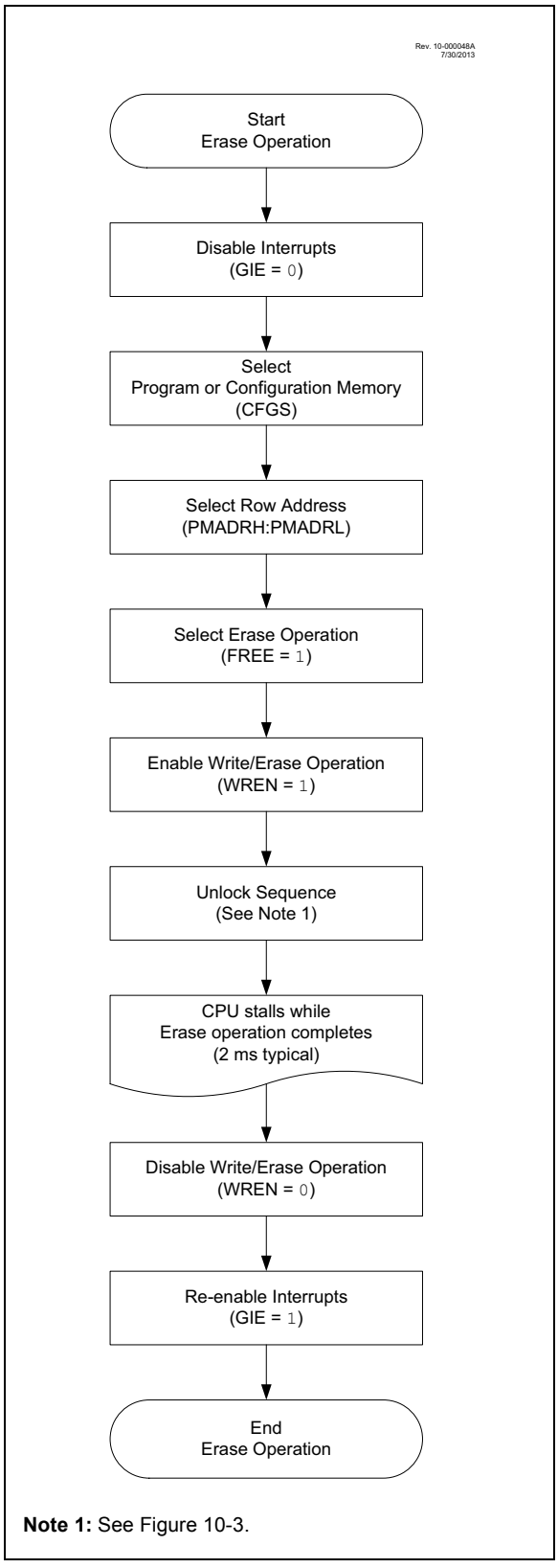
While executing code, program memory can only be erased by rows. To erase a row:

1. Load the PMADRH:PMADRL register pair with any address within the row to be erased.
2. Clear the CFGS bit of the PMCON1 register.
3. Set the FREE and WREN bits of the PMCON1 register.
4. Write 55h, then AAh, to PMCON2 (Flash programming unlock sequence).
5. Set control bit WR of the PMCON1 register to begin the erase operation.

See Example 10-2.

After the "`BSF PMCON1,WR`" instruction, the processor requires two cycles to set up the erase operation. The user must place two `NOP` instructions after the WR bit is set. The processor will halt internal operations for the typical 2 ms erase time. This is not Sleep mode as the clocks and peripherals will continue to run. After the erase cycle, the processor will resume operation with the third instruction after the PMCON1 write instruction.

FIGURE 10-4: FLASH PROGRAM MEMORY ERASE FLOWCHART



Note 1: See Figure 10-3.

10.6 Register Definitions: Flash Program Memory Control

REGISTER 10-1: PMDATL: PROGRAM MEMORY DATA LOW BYTE REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
PMDAT<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **PMDAT<7:0>**: Read/write value for Least Significant bits of program memory

REGISTER 10-2: PMDATH: PROGRAM MEMORY DATA HIGH BYTE REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	PMDAT<13:8>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **PMDAT<13:8>**: Read/write value for Most Significant bits of program memory

REGISTER 10-3: PMADRL: PROGRAM MEMORY ADDRESS LOW BYTE REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
PMADR<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **PMADR<7:0>**: Specifies the Least Significant bits for program memory address

REGISTER 10-4: PMADRH: PROGRAM MEMORY ADDRESS HIGH BYTE REGISTER

U-1	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—(1)	PMADR<14:8>						
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **Unimplemented:** Read as ‘1’

bit 6-0 **PMADR<14:8>**: Specifies the Most Significant bits for program memory address

Note 1: Unimplemented, read as ‘1’.

REGISTER 11-5: WPUA: WEAK PULL-UP PORTA REGISTER

U-0	U-0	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
—	—	WPUA5	WPUA4	WPUA3	WPUA2	WPUA1	WPUA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **WPUA<5:0>**: Weak Pull-up Register bits(3)
1 = Pull-up enabled
0 = Pull-up disabled

Note 1: Global $\overline{\text{WPUEN}}$ bit of the OPTION_REG register must be cleared for individual pull-ups to be enabled.
2: The weak pull-up device is automatically disabled if the pin is configured as an output.
3: For the WPUA3 bit, when MCLRE = 1, weak pull-up is internally enabled, but not reported here.

REGISTER 11-6: ODCONA: PORTA OPEN-DRAIN CONTROL REGISTER

U-0	U-0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0
—	—	ODA5	ODA4	—	ODA2	ODA1	ODA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

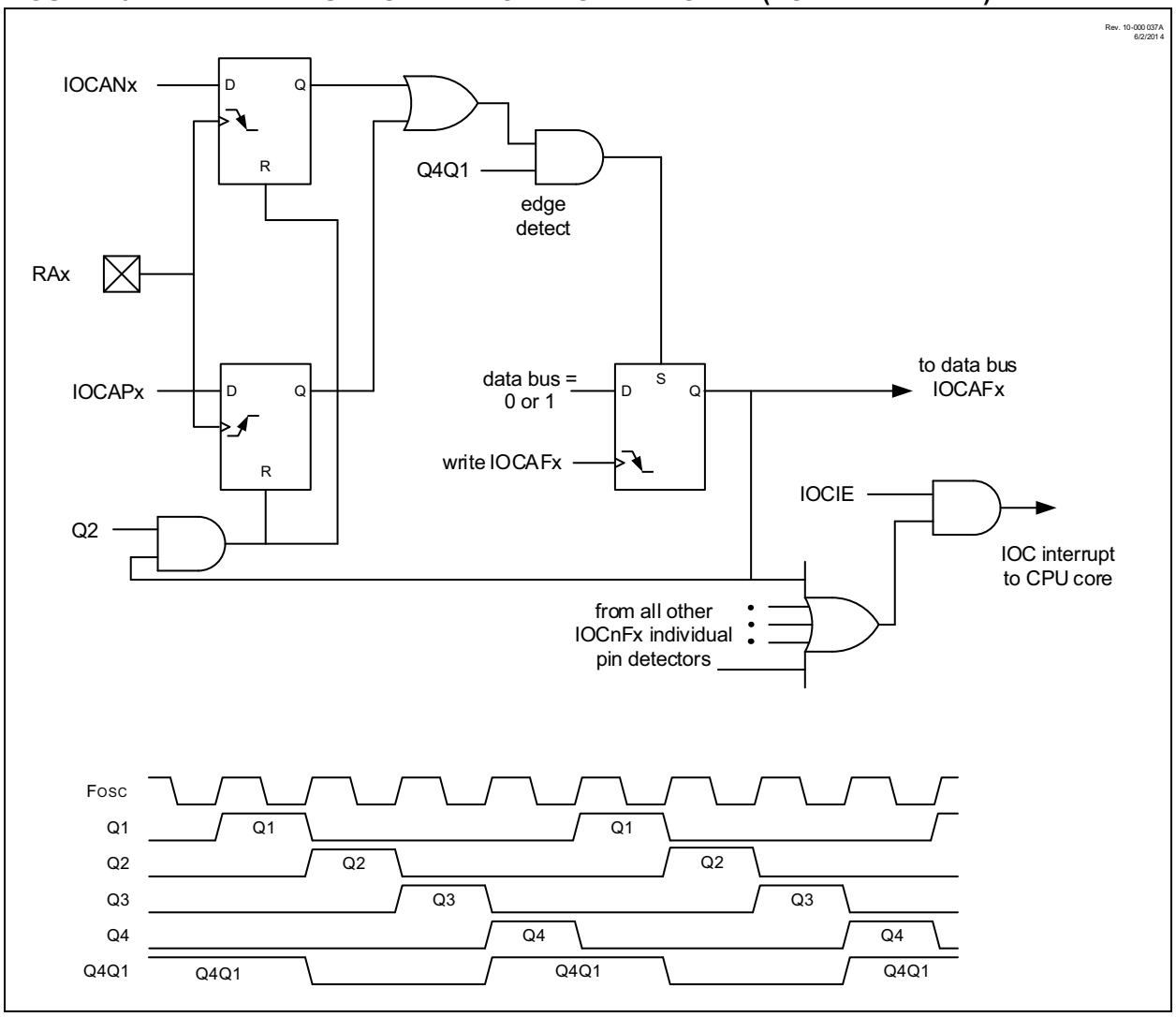
bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **ODA<5:4>:** PORTA Open-Drain Enable bits
For RA<5:4> pins, respectively
1 = Port pin operates as open-drain drive (sink current only)
0 = Port pin operates as standard push-pull drive (source and sink current)

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **ODA<2:0>:** PORTA Open-Drain Enable bits
For RA<2:0> pins, respectively
1 = Port pin operates as open-drain drive (sink current only)
0 = Port pin operates as standard push-pull drive (source and sink current)

FIGURE 13-1: INTERRUPT-ON-CHANGE BLOCK DIAGRAM (PORTA EXAMPLE)



REGISTER 13-4: IOCBP: INTERRUPT-ON-CHANGE PORTB POSITIVE EDGE REGISTER(1)

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	U-0	U-0
IOCBP7	IOCBP6	IOCBP5	IOCBP4	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **IOCBP<7:4>**: Interrupt-on-Change PORTB Positive Edge Enable bits
1 = Interrupt-on-Change enabled on the pin for a positive going edge. IOCBFx bit and IOCIF flag will be set upon detecting an edge.
0 = Interrupt-on-Change disabled for the associated pin.

bit 3-0 **Unimplemented:** Read as '0'

Note 1: PORTB functions available on PIC16(L)F1578/9 devices only.

REGISTER 13-5: IOCBN: INTERRUPT-ON-CHANGE PORTB NEGATIVE EDGE REGISTER(1)

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	U-0	U-0
IOCBN7	IOCBN6	IOCBN5	IOCBN4	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **IOCBN<7:4>**: Interrupt-on-Change PORTB Negative Edge Enable bits
1 = Interrupt-on-Change enabled on the pin for a negative going edge. IOCBFx bit and IOCIF flag will be set upon detecting an edge.
0 = Interrupt-on-Change disabled for the associated pin.

bit 3-0 **Unimplemented:** Read as '0'

Note 1: PORTB functions available on PIC16(L)F1578/9 devices only.

REGISTER 13-6: IOCBF: INTERRUPT-ON-CHANGE PORTB FLAG REGISTER(1)

R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0	R/W/HS-0/0	U-0	U-0	U-0	U-0
IOCBF7	IOCBF6	IOCBF5	IOCBF4	—	—	—	—
bit 7							bit 0

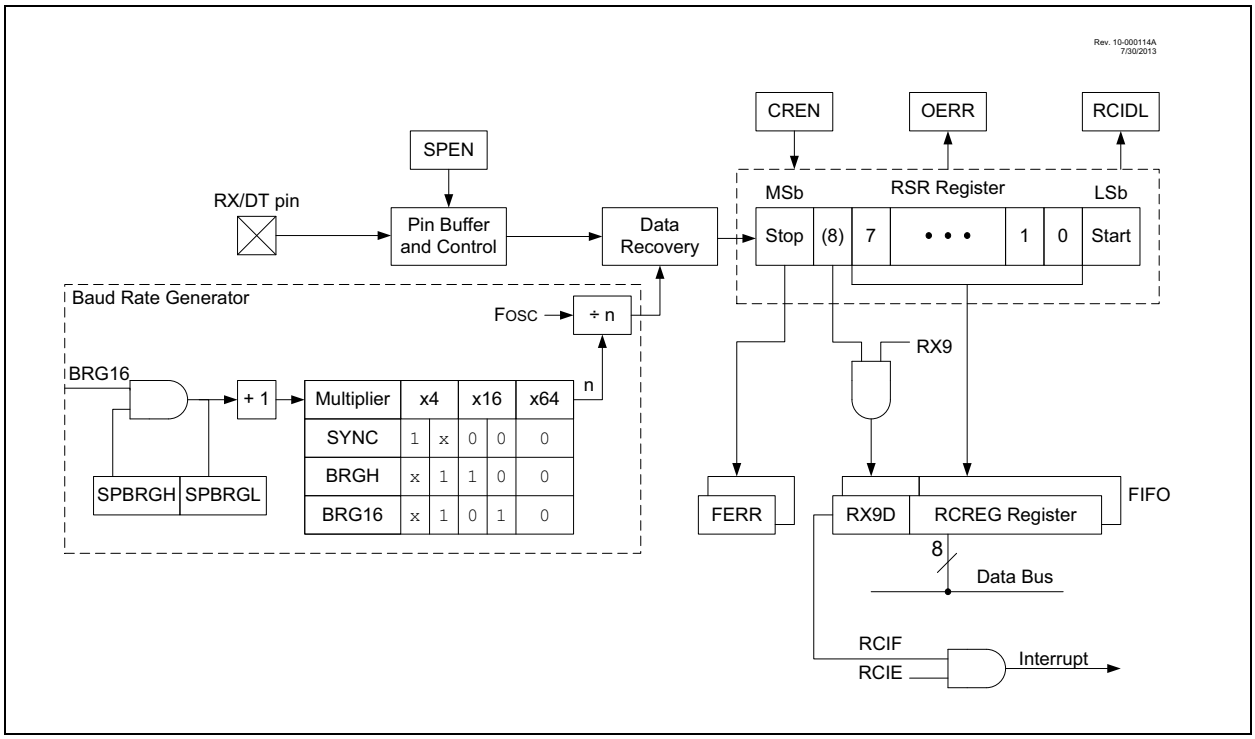
Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	HS - Bit is set in hardware

bit 7-4 **IOCBF<7:4>**: Interrupt-on-Change PORTB Flag bits
1 = An enabled change was detected on the associated pin.
Set when IOCBPx = 1 and a rising edge was detected on RBx, or when IOCBNx = 1 and a falling edge was detected on RBx.
0 = No change was detected, or the user cleared the detected change.

bit 3-0 **Unimplemented:** Read as '0'

Note 1: PORTB functions available on PIC16(L)F1578/9 devices only.

FIGURE 22-2: EUSART RECEIVE BLOCK DIAGRAM



The operation of the EUSART module is controlled through three registers:

- Transmit Status and Control (TXSTA)
- Receive Status and Control (RCSTA)
- Baud Rate Control (BAUDCON)

These registers are detailed in Register 22-1, Register 22-2 and Register 22-3, respectively.

When the receiver or transmitter section is not enabled then the corresponding RX or TX pin may be used for general purpose input and output.

TABLE 23-2: SUMMARY OF REGISTERS ASSOCIATED WITH PWM

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
OSCCON	SPLLEN	IRCF<3:0>				—	SCS<1:0>		69
PIE3	PWM4IE	PWM3IE	PWM2IE	PWM1IE	—	—	—	—	89
PIR3	PWM4IF	PWM3IF	PWM2IF	PWM1IF	—	—	—	—	92
PWMEN	—	—	—	—	PWM4EN_A	PWM3EN_A	PWM2EN_A	PWM1EN_A	243
PWMLD	—	—	—	—	PWM4LDA_A	PWM3LDA_A	PWM2LDA_A	PWM1LDA_A	243
PWMOUT	—	—	—	—	PWM4OUT_A	PWM3OUT_A	PWM2OUT_A	PWM1OUT_A	243
PWM1PHL	PH<7:0>								238
PWM1PHH	PH<15:8>								238
PWM1DCL	DC<7:0>								239
PWM1DCH	DC<15:8>								239
PWM1PRL	PR<7:0>								240
PWM1PRH	PR<15:8>								240
PWM1OFL	OF<7:0>								241
PWM1OFH	OF<15:8>								241
PWM1TMRL	TMR<7:0>								242
PWM1TMRH	TMR<15:8>								242
PWM1CON	EN	—	OUT	POL	MODE<1:0>		—	—	233
PWM1INTE	—	—	—	—	OFIE	PHIE	DCIE	PRIE	234
PWM1INTF	—	—	—	—	OFIF	PHIF	DCIF	PRIF	234
PWM1CLKCON	—	PS<2:0>			—	—	CS<1:0>		235
PWM1LDCON	LDA	LDT	—	—	—	—	LDS<1:0>		236
PWM1OFCON	—	OFM<1:0>		OFO	—	—	OFS<1:0>		237
PWM2PHL	PH<7:0>								238
PWM2PHH	PH<15:8>								238
PWM2DCL	DC<7:0>								239
PWM2DCH	DC<15:8>								239
PWM2PRL	PR<7:0>								240
PWM2PRH	PR<15:8>								240
PWM2OFL	OF<7:0>								241
PWM2OFH	OF<15:8>								241
PWM2TMRL	TMR<7:0>								242
PWM2TMRH	TMR<15:8>								242
PWM2CON	EN	—	OUT	POL	MODE<1:0>		—	—	233
PWM2INTE	—	—	—	—	OFIE	PHIE	DCIE	PRIE	234
PWM2INTF	—	—	—	—	OFIF	PHIF	DCIF	PRIF	234
PWM2CLKCON	—	PS<2:0>			—	—	CS<1:0>		235
PWM2LDCON	LDA	LDT	—	—	—	—	LDS<1:0>		236
PWM2OFCON	—	OFM<1:0>		OFO	—	—	OFS<1:0>		237
PWM3PHL	PH<7:0>								238
PWM3PHH	PH<15:8>								238
PWM3DCL	DC<7:0>								239
PWM3DCH	DC<15:8>								239
PWM3PRL	PR<7:0>								240
PWM3PRH	PR<15:8>								240
PWM3OFL	OF<7:0>								241
PWM3OFH	OF<15:8>								241
PWM3TMRL	TMR<7:0>								242
PWM3TMRH	TMR<15:8>								242
PWM3CON	EN	—	OUT	POL	MODE<1:0>		—	—	233
PWM3INTE	—	—	—	—	OFIE	PHIE	DCIE	PRIE	234
PWM3INTF	—	—	—	—	OFIF	PHIF	DCIF	PRIF	234

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by PWM.

TABLE 24-2: SUMMARY OF REGISTERS ASSOCIATED WITH CWG

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	—	ANSA4	—	ANSA2	ANSA1	ANSA0	121
CWG1CON0	G1EN	—	—	G1POLB	G1POLA	—	—	G1CS0	253
CWG1CON1	G1ASDLB<1:0>		G1ASDLA<1:0>		—	G1IS<2:0>			254
CWG1CON2	G1ASE	G1ARSEN	—	—	G1ASDSC2	G1ASDSC1	G1ASDSPPS	—	255
CWG1DBF	—	—	CWG1DBF<5:0>						256
CWG1DBR	—	—	CWG1DBR<5:0>						256
TRISA	—	—	TRISA5	TRISA4	—(1)	TRISA2	TRISA1	TRISA0	120

Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by CWG.
Note 1: Unimplemented, read as '1'.

TABLE 27-2: SUPPLY CURRENT (I_{DD})(1,2)

PIC16LF1574/5/8/9		Standard Operating Conditions (unless otherwise stated)					
PIC16F1574/5/8/9							
Param. No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						V_{DD}	Note
D013		—	41	51	µA	1.8	F_{OSC} = 1 MHz, External Clock (ECM), Medium Power mode
		—	69	80	µA	3.0	
D013		—	79	107	µA	2.3	F_{OSC} = 1 MHz, External Clock (ECM), Medium Power mode
		—	105	138	µA	3.0	
		—	151	184	µA	5.0	
D014		—	134	152	µA	1.8	F_{OSC} = 4 MHz, External Clock (ECM), Medium Power mode
		—	234	268	µA	3.0	
D014		—	201	255	µA	2.3	F_{OSC} = 4 MHz, External Clock (ECM), Medium Power mode
		—	270	329	µA	3.0	
		—	344	431	µA	5.0	
D015		—	7	19	µA	1.8	F_{OSC} = 31 kHz, LFINTOSC, -40°C ≤ T_A ≤ +85°C
		—	9	20	µA	3.0	
D015		—	15	25	µA	2.3	F_{OSC} = 31 kHz, LFINTOSC, -40°C ≤ T_A ≤ +85°C
		—	18	28	µA	3.0	
		—	20	29	µA	5.0	
D016		—	128	174	µA	1.8	F_{OSC} = 500 kHz, MFINTOSC
		—	153	203	µA	3.0	
D016		—	166	241	µA	2.3	F_{OSC} = 500 kHz, MFINTOSC
		—	187	273	µA	3.0	
		—	249	332	µA	5.0	
D017*		—	0.6	0.7	mA	1.8	F_{OSC} = 8 MHz, HFINTOSC
		—	0.9	1.1	mA	3.0	
D017*		—	0.7	1.0	mA	2.3	F_{OSC} = 8 MHz, HFINTOSC
		—	1.0	1.1	mA	3.0	
		—	1.1	1.2	mA	5.0	
D018		—	0.9	1.0	mA	1.8	F_{OSC} = 16 MHz, HFINTOSC
		—	1.3	1.4	mA	3.0	
D018		—	1.1	1.3	mA	2.3	F_{OSC} = 16 MHz, HFINTOSC
		—	1.3	1.5	mA	3.0	
		—	1.5	1.8	mA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all I_{DD} measurements in active operation mode are: CLKIN = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{SS}; $\overline{MCLR}$ = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: PLL required for 32 MHz operation.

TABLE 27-5: MEMORY PROGRAMMING SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
		Program Memory Programming Specifications					
D110	VIHH	Voltage on $\overline{MCLR}$/VPP pin	8.0	—	9.0	V	**(Note 2)**
D111	IDDP	Supply Current during Programming	—	—	10	mA	
D112	VBE	VDD for Bulk Erase	2.7	—	VDDMAX	V	
D113	VPEW	VDD for Write or Row Erase	VDDMIN	—	VDDMAX	V	
D114	IPPPGM	Current on $\overline{MCLR}$/VPP during Erase/Write	—	1.0	—	mA	
D115	IDDPGM	Current on VDD during Erase/Write	—	5.0	—	mA	
		Program Flash Memory					
D121	EP	Cell Endurance	10K	—	—	E/W	-40°C ≤ TA ≤ +85°C **(Note 1)**
D122	VPRW	VDD for Read/Write	VDDMIN	—	VDDMAX	V	
D123	TIW	Self-timed Write Cycle Time	—	2	2.5	ms	
D124	TRETD	Characteristic Retention	—	40	—	Year	Provided no other specifications are violated
D125	EHEFC	High-Endurance Flash Cell	100K	—	—	E/W	0°C ≤ TA ≤ +60°C, lower byte last 128 addresses

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Self-write and Block Erase.

2: Required only if single-supply programming is disabled.

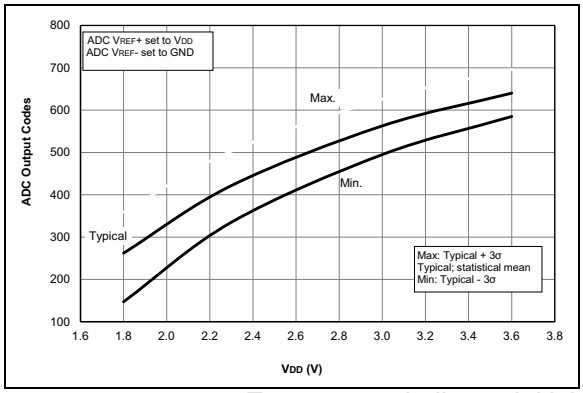


FIGURE 28-67: *Temperature Indicator Initial Offset, Low Range, Temp = 20°C, LF Devices Only.*

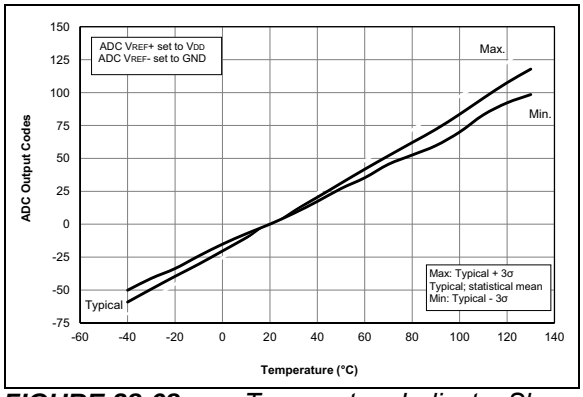


FIGURE 28-68: *Temperature Indicator Slope Normalized TO 20°C, High Range, VDD = 5.5V, F Devices Only.*

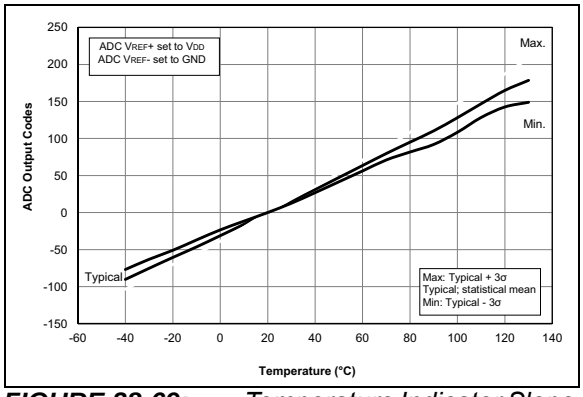


FIGURE 28-69: *Temperature Indicator Slope Normalized TO 20°C, High Range, VDD = 3.6V, F Devices Only.*

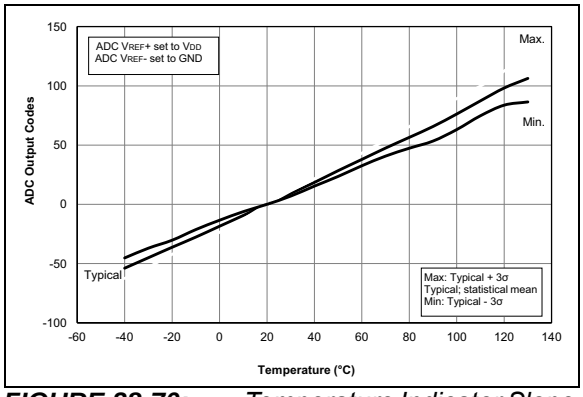


FIGURE 28-70: *Temperature Indicator Slope Normalized TO 20°C, Low Range, VDD = 3.0V, F Devices Only.*

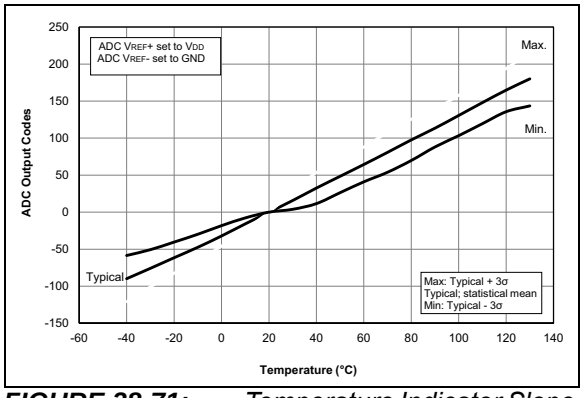


FIGURE 28-71: *Temperature Indicator Slope Normalized TO 20°C, Low Range, VDD = 1.8V, LF Devices Only.*

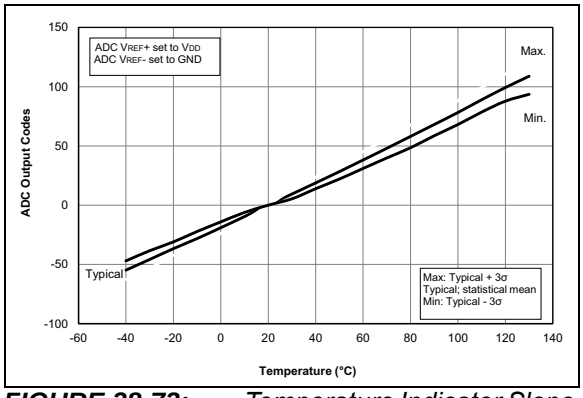


FIGURE 28-72: *Temperature Indicator Slope Normalized TO 20°C, Low Range, VDD = 3.0V, LF Devices Only.*

29.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

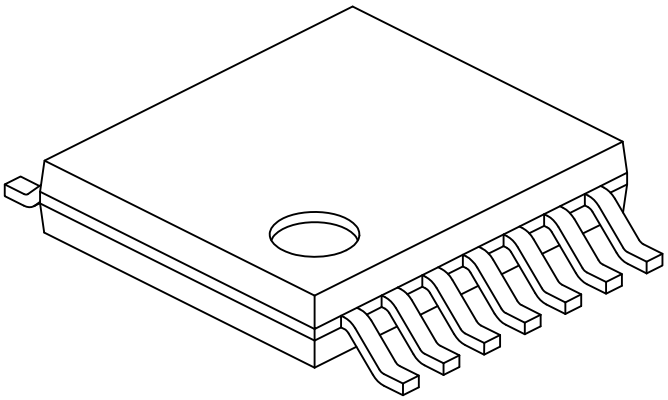
29.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		0.65 BSC	
Overall Height	A	-	-	1.20
Molded Package Thickness	A2	0.80	1.00	1.05
Standoff	A1	0.05	-	0.15
Overall Width	E		6.40 BSC	
Molded Package Width	E1	4.30	4.40	4.50
Molded Package Length	D	4.90	5.00	5.10
Foot Length	L	0.45	0.60	0.75
Footprint	(L1)		1.00 REF	
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.09	-	0.20
Lead Width	b	0.19	-	0.30

Notes:

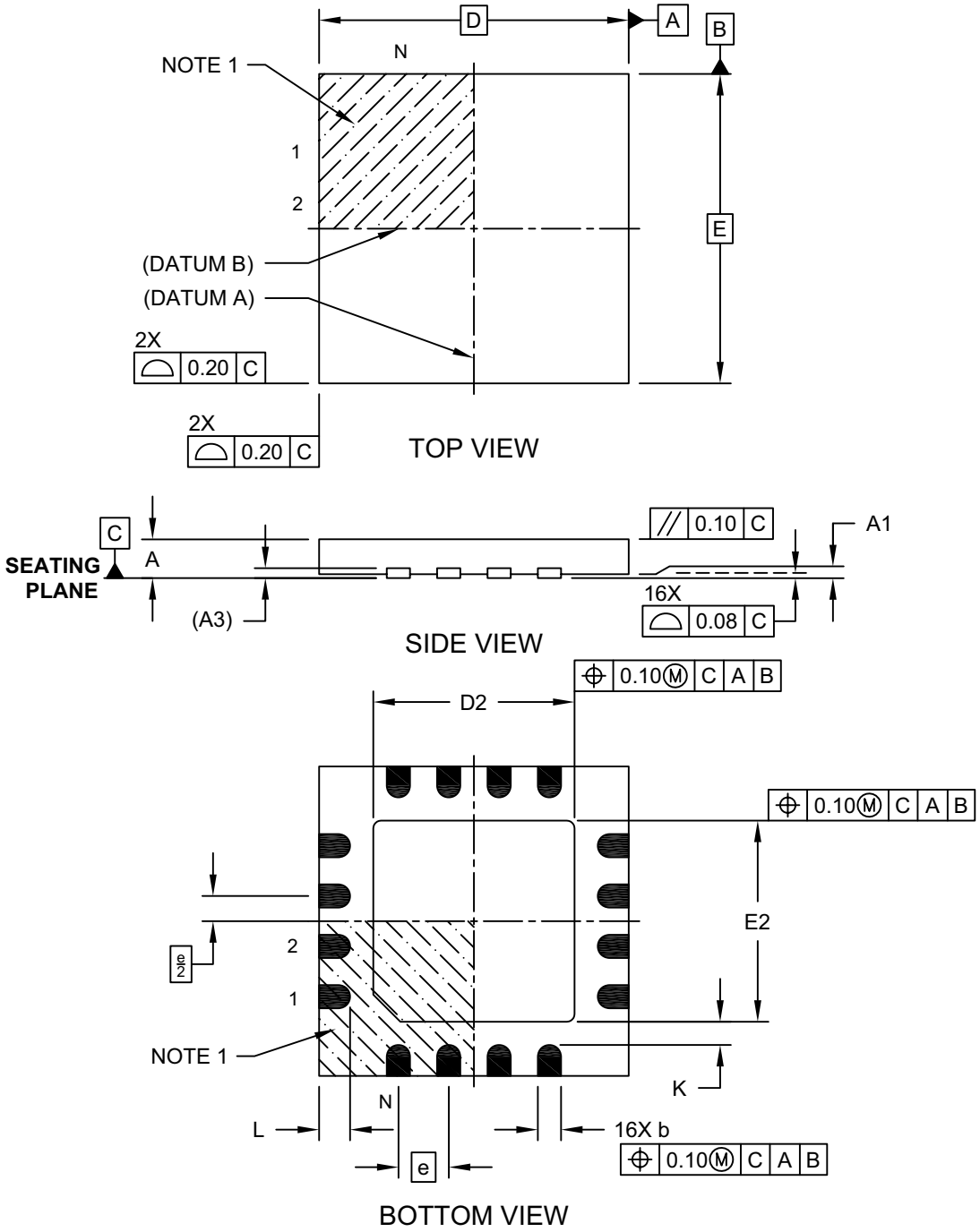
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-087C Sheet 2 of 2

16-Lead Ultra Thin Plastic Quad Flat, No Lead Package (JQ) - 4x4x0.5 mm Body [UQFN]

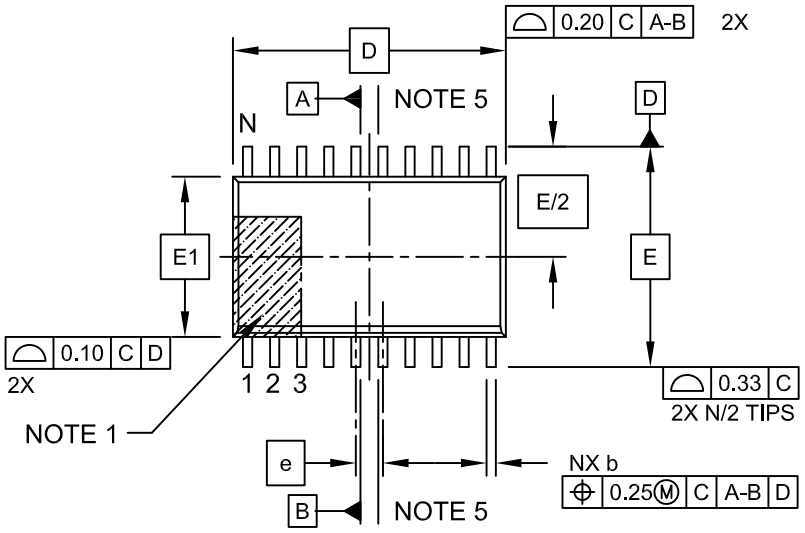
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



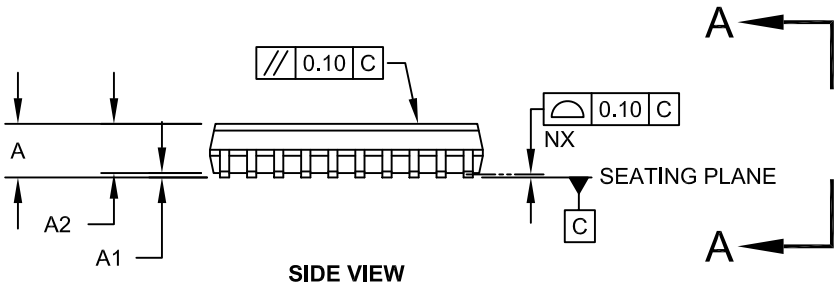
Microchip Technology Drawing C04-257A Sheet 1 of 2

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

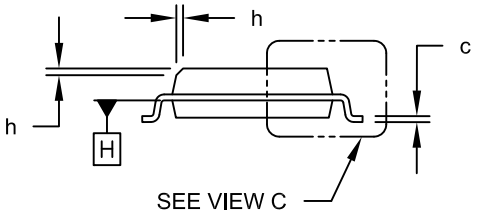
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

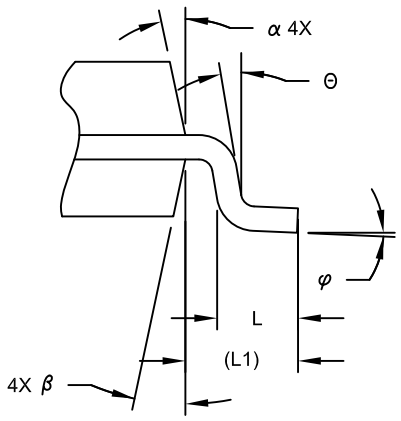


VIEW A-A

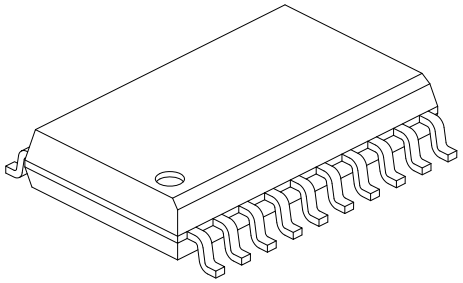
Microchip Technology Drawing C04-094C Sheet 1 of 2

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		12.80 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-094C Sheet 2 of 2